

Abstract

**A HOUSING FOR SEMICONDUCTOR DEVICES, SEMICONDUCTOR DEVICE
PIN, AND METHOD FOR THE MANUFACTURING OF PINS**

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A housing, in particular for semiconductor devices, a semiconductor device pin, and a method for the manufacturing of pins wherein at least one pin is punched out from a basic body, in particular a lead framed, by means of one or a plurality of punching process steps, wherein the pin is coated with a separate metal layer after the final punching out of said pin.

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